ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH THROUGH SEMICONDUCTOR VIAS AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit package system including: providing a package substrate; mounting a first integrated circuit die, having through silicon vias, on the package substrate; coupling cylindrical studs to the package substrate adjacent to the first integrated circuit die; and mounting a second integrated circuit die, having through silicon vias, on the first integrated circuit die and the cylindrical studs for forming an electrical connection among the second integrated circuit die, the first integrated circuit die, the package substrate, or a combination thereof.

(Fig. 1)